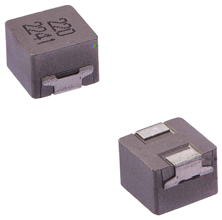
SMD Low Profile High Current Molded Inductor
Size 8054



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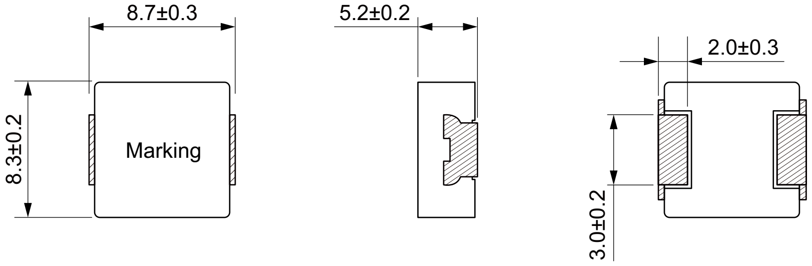
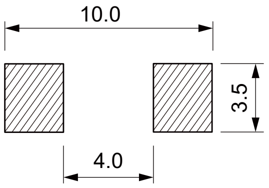
Dimensions: [mm]

Land Pattern: [mm]



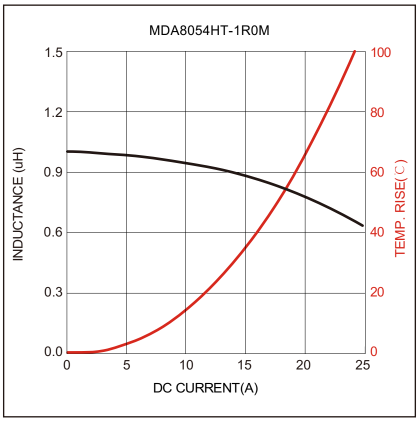


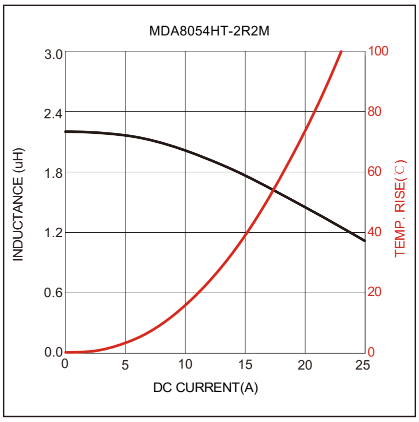
Electrical Properties:

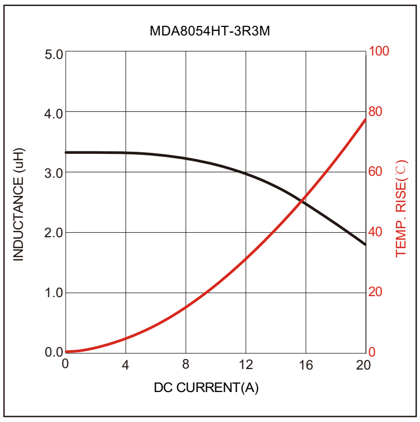
	(μH)				Saturation	Saturation	(mΩ)	(mΩ)

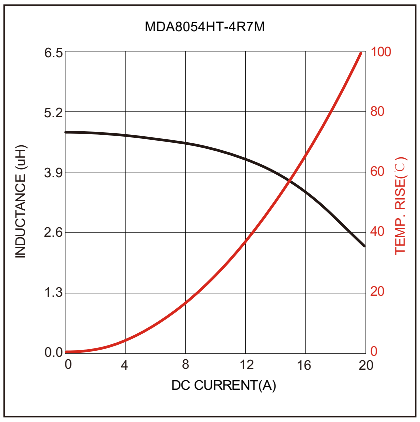
Saturation Current will cause L to drop approximately 35%
Temperature Rise Current: The actual value of DC current when the temperature rise is △T=40°C

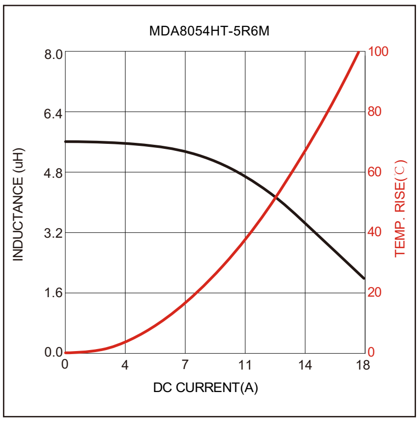
Typical Electrical Characteristics:

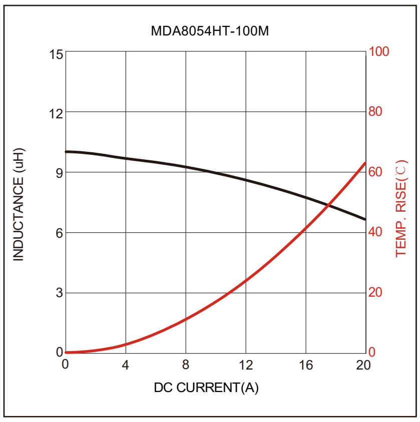

MDA8054HT-1R0M

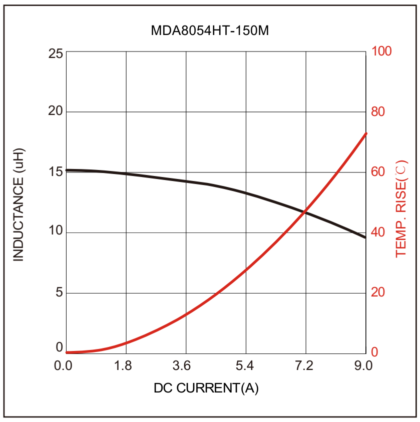

MDA8054HT-2R2M

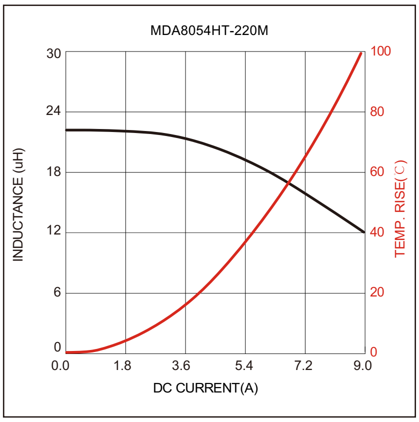

MDA8054HT-3R3M

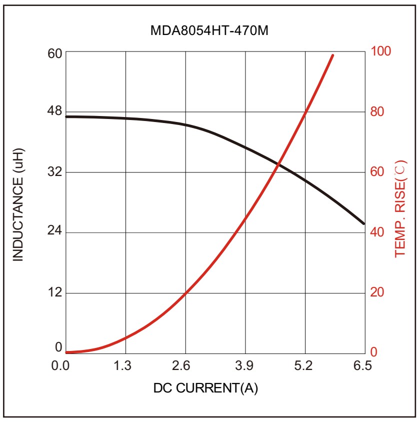

MDA8054HT-4R7M


MDA8054HT-5R6M

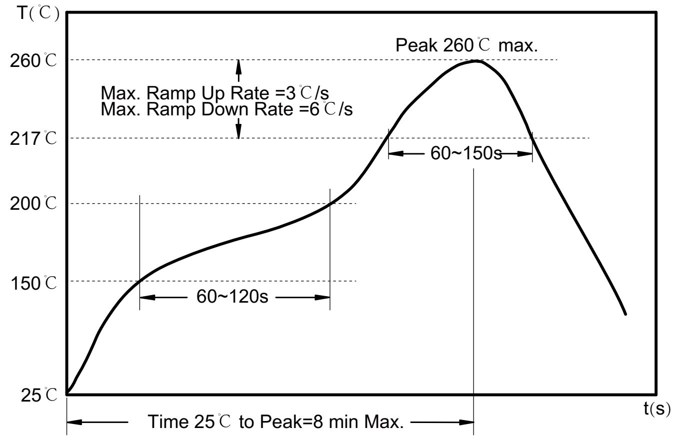

MDA8054HT-100M


MDA8054HT-150M


MDA8054HT-220M


MDA8054HT-470M

Soldering Reflow:



Preheat condition: 150 ~200℃/ 60~120 sec.

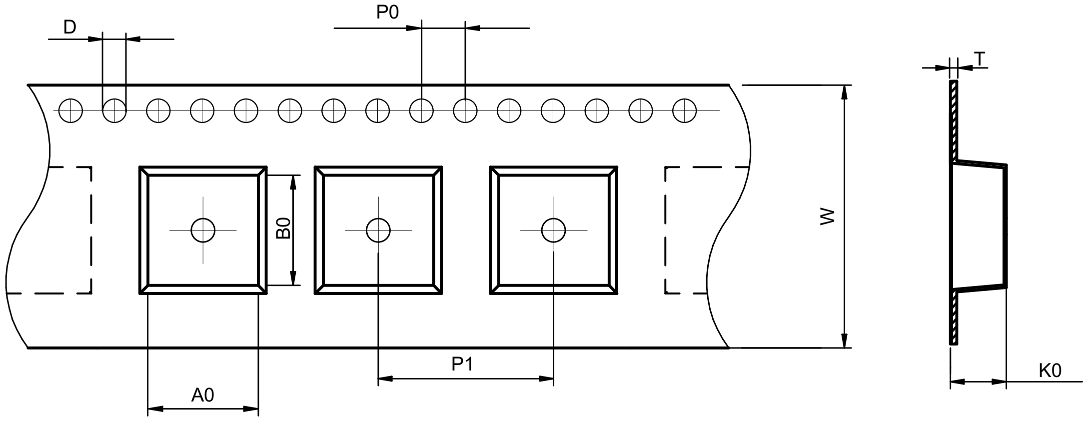
Allowed time above 217℃: 60~150 sec.

Max temperature: 260℃.

Allowed Reflow time: 2x max.

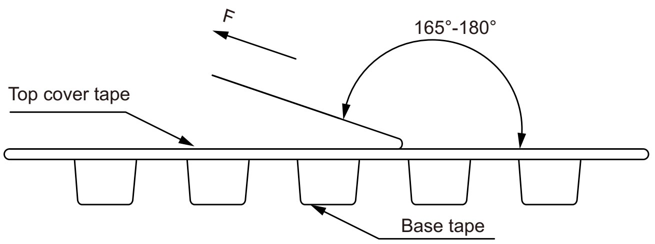
Packaging Information:

Tape Dimension:



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	T (mm)
MDA8054HT	8.9±0.1	9.0±0.1	1.5±0.1	4.0±0.1	16.0±0.1	24.0±0.3	5.9±0.1	0.40±0.05

Peel force of top cover tape:

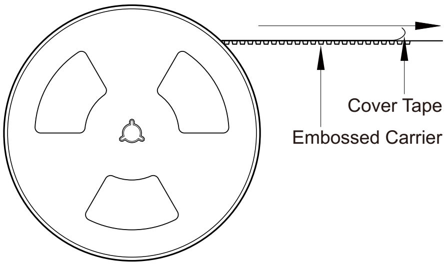


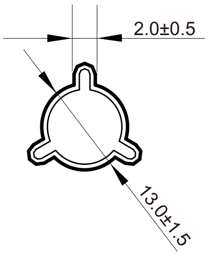
The peel force of top cover tape shall be between 0.1 to 1.27 N

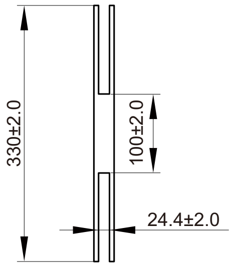
Product Marking:

Marking	Printing (Inductance+period)

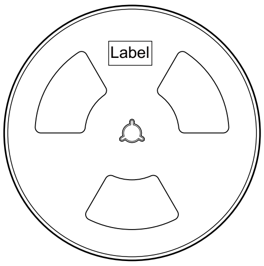
Reel Dimension： [mm]



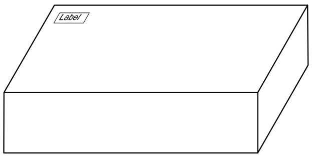




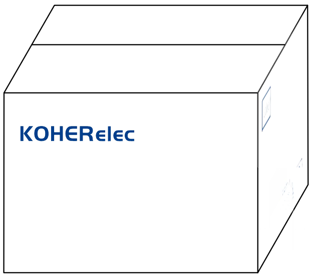
Packaging Quantity:



500 Pcs/Reel



2 Reel /Inner box(1000 Pcs)



3 Inner box/Carton box(3K Pcs)

Cautions and Warnings:

Storage Conditions：

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max).If the storage period elapses, the soldering of the terminal electrodes may deteriorate.The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components.The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications.If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does.As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.